

in Silicone resin

Solvent based coatings

Evonik Tego formulation No. 304

Rev. Number: 01.01

08/07

Function	Product	Producer	PBW
Methyl phenyl silicone resin	SILIKOPHEN® P80/X	Evonik	34.40
Copper chromite black spinel	HEUCODUR® Black 9-100	Sudarshan	8.00
Carbon black pigment	PRINTEX® L	Orion Engineered Carbons	2.00
Mica/quartz/chlorite filler	Plastorit® 0000	Imerys	6.00
Anticorrosive pigment	HEUCOPHOS® ZPO	Sudarshan	6.00
Grind.			
Solvent	Xylene		1.50
Solvent	Isopropyl alcohol		0.05
Wetting and dispersing agent	TEGO® Dispers 700	Evonik	0.15
Rheology modifier	BENTONE® 38	Elementis	0.30
Mix until uniform paste prior to addition.			
Solvent	Xylene		30.60
Solvent	Butyl acetate		11.00
Add while stirring.			

100.00

Gf-SB10_004-01_01B

Disclaimer - The information given in this data sheet is based on the present state of our knowledge & is intended as a general description of our products & their possible applications. Neither do these data imply any guarantee of certain properties, nor the suitability of the product for a specific purpose. Because of the multitude of formulations, production & application conditions, all the above mentioned data have to be adjusted to the circumstances of the processor. As customer use lies beyond our knowledge and control, we cannot accept any liability relating to the use of our products in any particular application. In addition to that, the legal rights of third parties must always be considered. No liabilities, including those for patent rights, can be derived from this fact for individual cases. It cannot be ruled out that this product contains particles < 0.1 µm. Any user of this product is responsible for determining the suitability of Sudarshan's products for its particular application & to ensure that any proprietary rights & existing laws & legislation are observed.